

10/711,185

IN THE CLAIMS:

Please substitute the following claims for the same-numbered claims in the application:

1-20. (Cancelled).

21. (Previously Presented) A conductive interconnection for joining an integrated circuit device to a device carrier, said conductive interconnection comprising:

a polymer having a spherical shape between said integrated circuit device and said device carrier; and

micelle brushes on the outer surface of said polymer,

wherein a first end of said micelle brushes has an affinity for said polymer so as to attach said first end to said polymer and a second end of said micelle brushes has an affinity for metal surfaces so as to attach said second end to said integrated circuit device on one side of said polymer and said device carrier on another side of said polymer.

22. (Original) The conductive interconnection in claim 21, wherein said micelle brushes comprise a reactive moiety with an organic tail.

23. (Original) The conductive interconnection in claim 21, wherein said polymer includes metal particles.

24. (Original) The conductive interconnection in claim 21, wherein said polymer comprises a thermoset polymer.

25. (Original) The conductive interconnection in claim 21, wherein said polymer comprises a thermoplastic conductive adhesive.